

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC3R6SN10AH
Package Type :	PDFNWB5x6-8L-F

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
wafer	Si	7440-21-3	100.000%	2.724%
Lead Frame	P	7723-14-0	0.251%	33.809%
	Fe	7439-89-6	0.500%	
	Cu	7440-50-8	98.949%	
	Ag	7440-22-4	0.300%	
Die Attach	TIN - Sn	7440-31-5/231-141-8	16.000%	5.409%
	LEAD - Pb	7439-92-1/231-100-4	16.000%	
	SILVER - Ag	7440-22-4/231-131-3	2.804%	
	ANTIMONY - Sb	7440-36-0/231-146-5	10.000%	
	BISMUTH - Bi	7440-69-9/231-177-4	30.000%	
	INDIUM - Ln	7440-74-6/231-180-0	5.000%	
	COPPER - Cu	7440-50-8/231-159-6	0.196%	
	POILYGLYCOLETHER	9038-95-3	2.000%	
	CARBOXYLIC ACID	67762-36-1	1.000%	
	MODIFIED CASTER OIL	61788-85-0	3.000%	
	DODECYLPHENOL	27193-86-8	14.000%	
CLIP	CU	7440-50-8	99.602%	11.4%
	Pb	7439-92-1	0.008%	
	Fe	7439-89-6	0.152%	
	Zn	7440-66-6	0.008%	
	P	7723-14-0	0.228%	
Wire	Au	7440-57-5	99.854%	0.66%
	others	/	0.146%	
Mold Compound	Epoxy resin A	Trade Secret	5.000%	45.41%
	Epoxy resin B	Trade Secret	4.000%	
	curing agent	Trade Secret	5.000%	
	catalyst	Trade Secret	5.200%	
	Carbon black	1333-86-4	0.200%	
	Silica(Amorphous) A	60676-86-0	65.600%	
	Silica(Amorphous) B	7631-86-9	15.000%	
Plating	Sn	7440-31-5	99.498%	0.58%
	others	/	0.418%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.